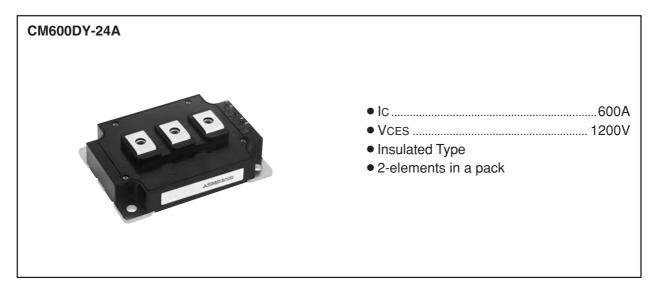
MITSUBISHI IGBT MODULES

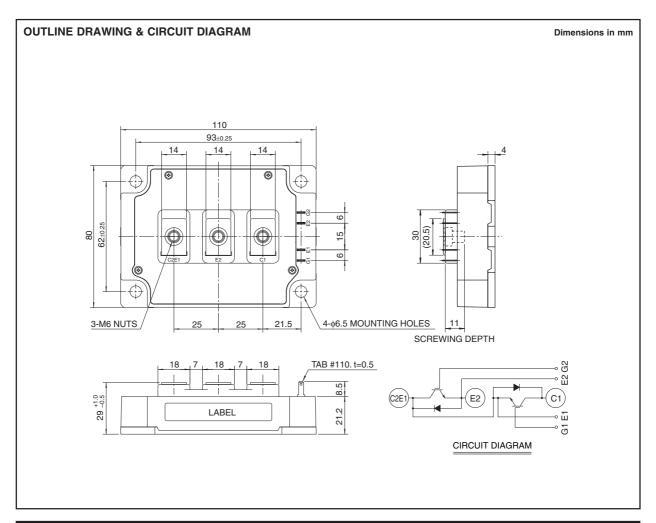
# CM600DY-24A

HIGH POWER SWITCHING USE



## **APPLICATION**

AC drive inverters & Servo controls, etc





## **HIGH POWER SWITCHING USE**

#### ABSOLUTE MAXIMUM RATINGS (Tj = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit	
VCES	Collector-emitter voltage	G-E Short	1200	V	
VGES	Gate-emitter voltage	C-E Short	±20	V	
Ic	Collector current	DC, $Tc = 78^{\circ}C^{*1}$	600	Α	
Ісм	Collector current	Pulse (Note	2) 1200		
IE (Note 1)	Emitter current		600	Α	
IEM (Note 1)	Emiller current	Pulse (Note	2) 1200		
PC (Note 3)	Maximum collector dissipation	$Tc = 25^{\circ}C^{*1}$	3670	W	
Tj	Junction temperature		<b>−40</b> ~ <b>+150</b>	°C	
Tstg	Storage temperature		<b>−40</b> ~ <b>+125</b>	°C	
Viso	Isolation voltage	Terminals to base plate, f = 60Hz, AC 1 minute	2500	Vrms	
_	Targue etropath	Main terminals M6 screw	3.5 ~ 4.5	N • m	
_	Torque strength	Mounting M6 screw	3.5 ~ 4.5		
_	Weight	Typical value	580	g	

## ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise specified)

Cumple al	Parameter	Test conditions		Limits			
Symbol	Parameter			Min.	Тур.	Max.	Unit
ICES	Collector cutoff current	VCE = VCES, VGE = 0V			_	1	mA
VGE(th)	Gate-emitter threshold voltage	IC = 60mA, VCE = 10V		6	7	8	٧
IGES	Gate leakage current	$\pm$ VGE = VGES, VCE = 0V		_	_	0.5	μΑ
Va=()	Collector-emitter saturation		Tj = 25°C	_	2.1	3.0	V
VCE(sat)	voltage	IC = 600A, VGE = 15V	Tj = 125°C	_	2.4	_	
Cies	Input capacitance	VCE = 10V VGE = 0V			_	94	nF
Coes	Output capacitance			_	_	8	
Cres	Reverse transfer capacitance			l	_	1.8	
QG	Total gate charge	Vcc = 600V, Ic = 600A, VGE = 15V		_	2700	_	nC
td(on)	Turn-on delay time	VCC = 600V, IC = 600A $VGE = \pm 15V$ $RG = 0.52\Omega, Inductive load IE = 600A$			_	660	ns
tr	Turn-on rise time			_	_	190	
td(off)	Turn-off delay time			_	_	700	
tf	Turn-off fall time				_	350	
trr (Note 1)	Reverse recovery time			_	_	250	ns
Qrr (Note 1)	Reverse recovery charge				19	_	μC
VEC(Note 1)	Emitter-collector voltage	IE = 600A, VGE = 0V		_	_	3.8	V
Rth(j-c)Q	Thermal resistance	IGBT part (1/2 module)*1			_	0.034	K/W
Rth(j-c)R	Thermal resistance	FWDi part (1/2 module)*1		_	_	0.062	
Rth(c-f)	Contact thermal resistance	Case to heat sink, Thermal compound Applied (1/2 module)*2		_	0.018	_	
Rg	External gate resistance			0.52	_	7.8	Ω

<sup>\*1 :</sup> Case temperature (Tc), heat sink temperature (Tt) measured point is just under the chips. \*2 : Typical value is measured by using thermally conductive grease of  $\lambda$  = 0.9[W/(m • K)].



Feb. 2009

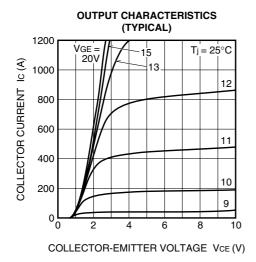
Note 1. IE, VEC, trr & Qrr represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).

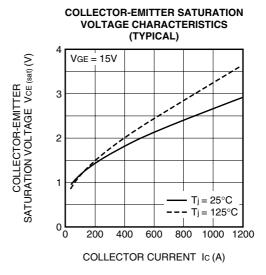
<sup>2.</sup> Pulse width and repetition rate should be such that the device junction temperature (Tj) does not exceed T<sub>jmax</sub> rating.

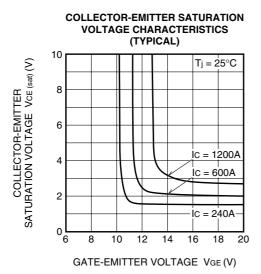
3. Junction temperature (Tj) should not increase beyond 150°C.

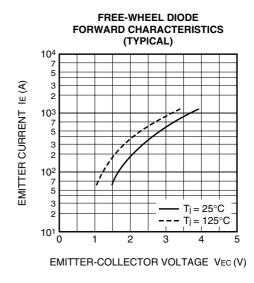
#### HIGH POWER SWITCHING USE

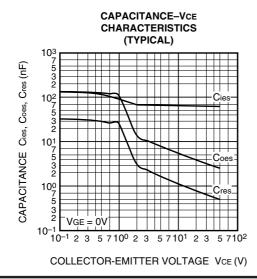
#### **PERFORMANCE CURVES**

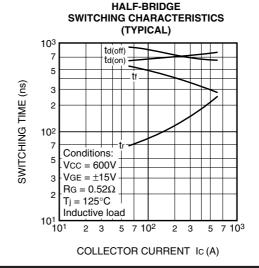












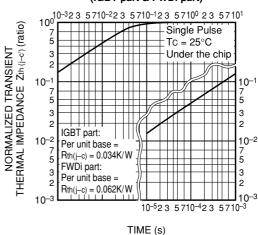
#### HIGH POWER SWITCHING USE

#### REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL) Irr (A) 10<sup>3</sup> trr (ns) REVERSE RECOVERY CURRENT 5 REVERSE RECOVERY TIME 3 2 102 tr 7 Conditions: 5 Vcc = 600V3 $VGE = \pm 15V$ $RG = 0.52\Omega$ 2 T<sub>i</sub> = 25°C 101 L 101 Inductive load

2

3 5

#### TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



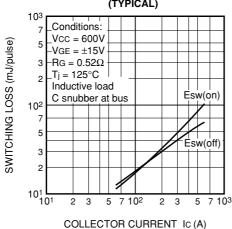
EMITTER CURRENT IE (A)

5 7 10<sup>3</sup>

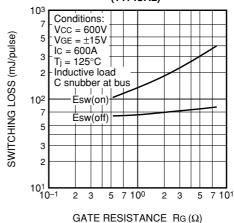
3

7 10<sup>2</sup>

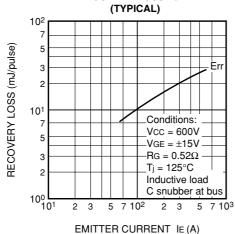
#### SWITCHING LOSS vs. **COLLECTOR CURRENT** (TYPICAL)



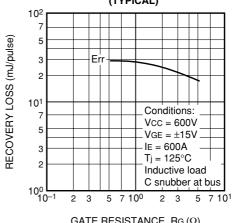
SWITCHING LOSS vs. **GATE RESISTANCE** (TYPICAL)



**RECOVERY LOSS vs. IE** 



RECOVERY LOSS vs. **GATE RESISTANCE** (TYPICAL)



GATE RESISTANCE RG  $(\Omega)$ 



## **HIGH POWER SWITCHING USE**

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